



SOT1167-1

plastic, thermal enhanced ultra thin small outline package; 12 terminals; 0.4 mm pitch; 2.5 mm x 1.35 mm x 0.55 mm body

30 January 2017

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN2514-12
Package type industry code	DFN2514-12
Package style descriptive code	HUSON (thermal enhanced ultra thin small outline; no leads)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	22-3-2010
Manufacturer package code	SOT1167

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.4	-	2.5	2.6	mm
E	package width	1.25	-	1.35	1.45	mm
A	seated height	-	-	-	0.55	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	12	-	

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2. Package outline

HUSON12: plastic, thermal enhanced ultra thin small outline package; no leads; 12 terminals; body 1.35 x 2.5 x 0.55 mm

SOT1167-1

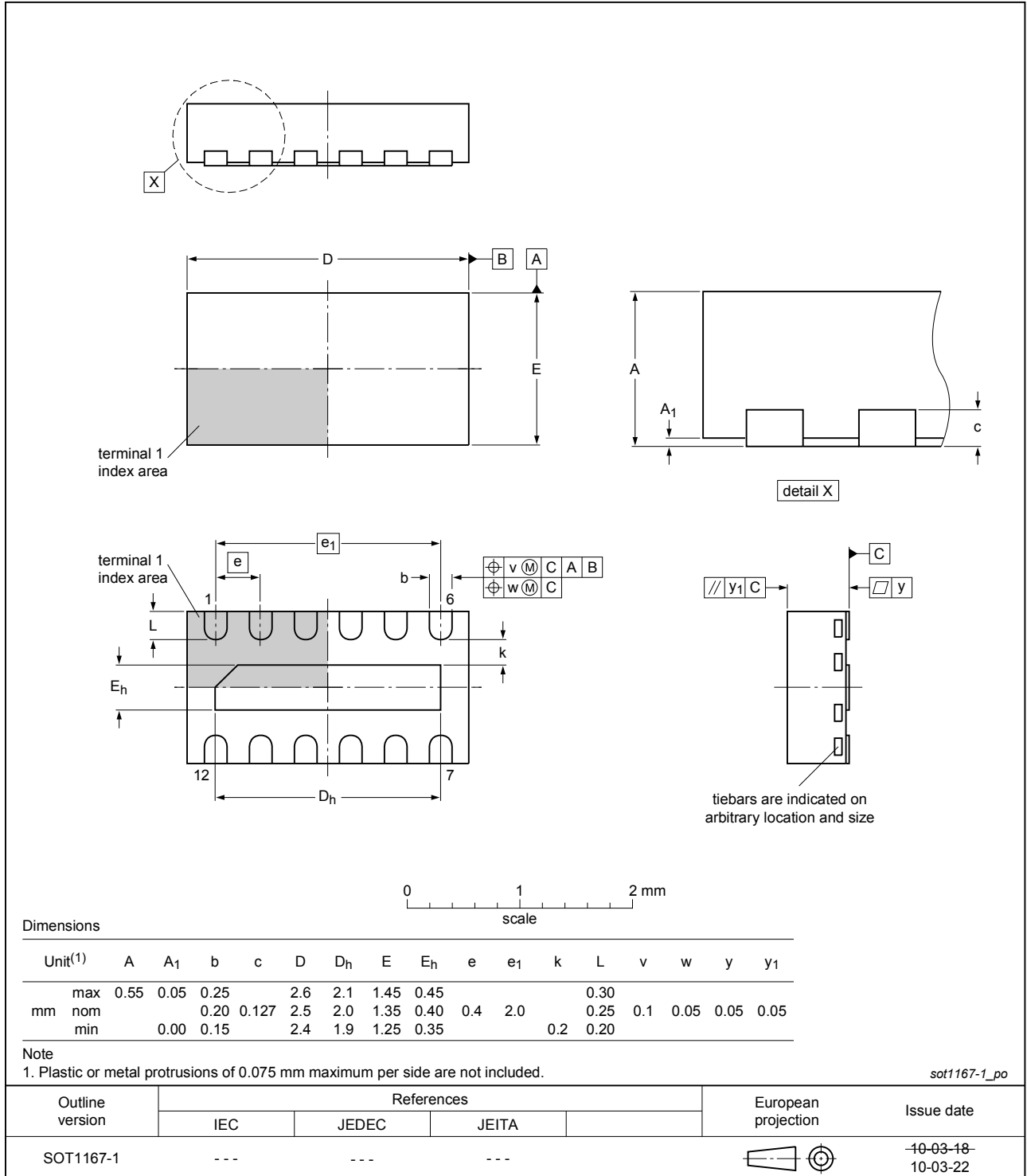


Fig. 1. Package outline DFN2514-12 (SOT1167-1)

plastic, thermal enhanced ultra thin small outline package; 12 terminals; 0.4 mm pitch; 2.5 mm x 1.35 mm x 0.55 mm body

3. Soldering

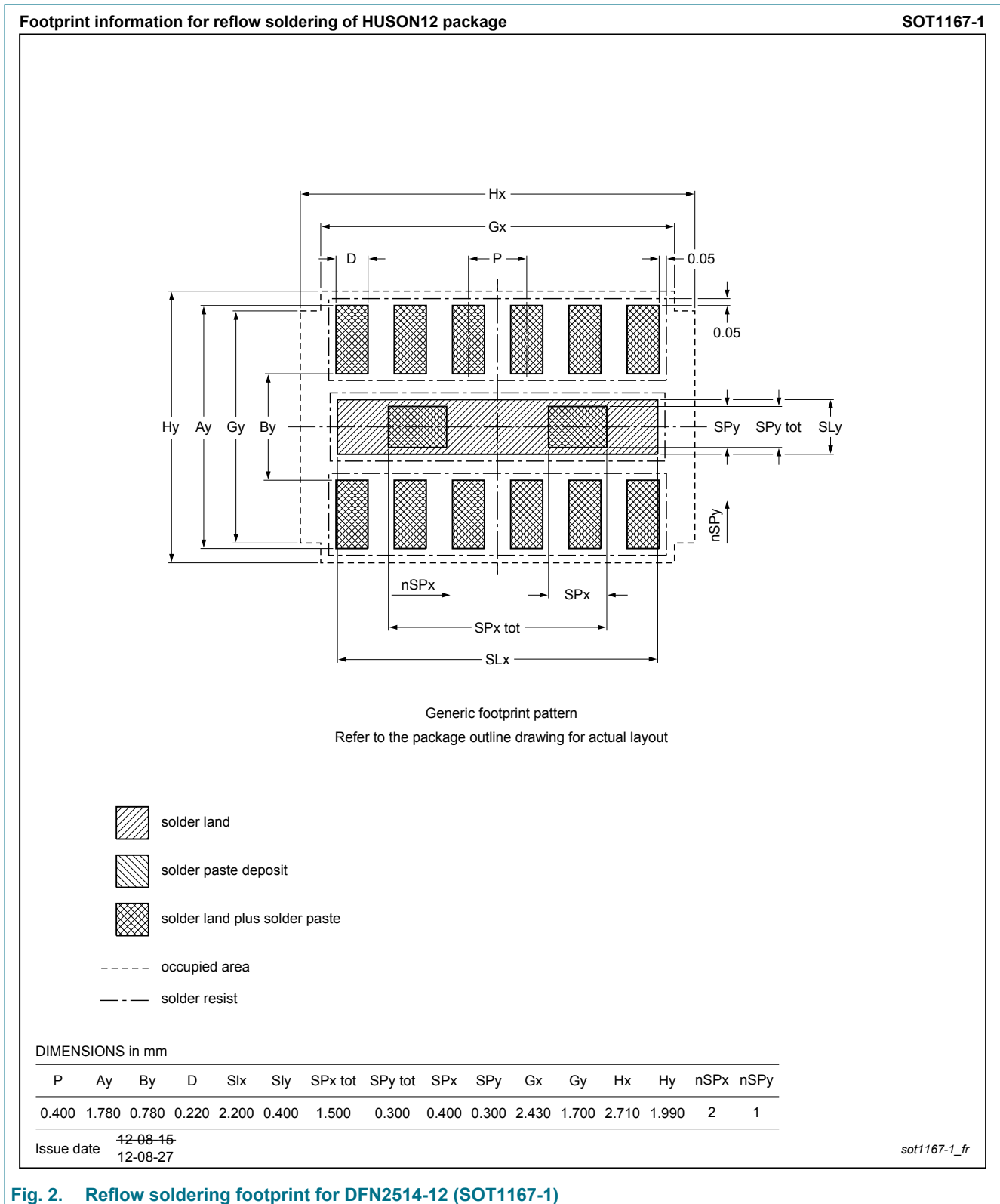


Fig. 2. Reflow soldering footprint for DFN2514-12 (SOT1167-1)

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4. Legal information

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